REMARKS

The specification has been amended to correct errors of a typographical and

grammatical nature. Due to the number of corrections thereto, applicants submit herewith a

Substitute Specification, along with a marked-up copy of the original specification for the

Examiner's convenience. The substitute specification includes the changes as shown in the

marked-up copy and includes no new matter. Therefore, entry of the Substitute Specification

is respectfully requested.

The abstract has also been amended to more clearly describe the features of the

present invention.

Entry of the preliminary amendments and examination of the application is respectfully

requested.

To the extent necessary, applicant's petition for an extension of time under 37 CFR 1.136.

Please charge any shortage in the fees due in connection with the filing of this paper, including

extension of time fees, to Deposit Account No. 01-2135 (Case: 503.39144X00) and please credit

any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS, LLP

William I. Solomon

Registration No. 28,565

DRA/WIS/jla (703) 312-6600

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IN THE TITLE:

Electroless Copper Plating Machine Thereof, And Multi-Layer Printed Wiring Board ABSTRACT <u>OF THE DISCLOSURE</u>

The main purpose of the present invention is to provide a A method of is provided for removing plating blocking ions, such as anions, in pairs with copper ions and oxidant ions of the a copper ion reducing agent from the an electroless copper plating solution and keeping a constant salt concentration in the electroless copper plating solution during plating, a device to realize said method, and applications thereof. For An The electroless copper plating method, a device thereof, and application thereof, using uses a plating solution containing copper sulfate as copper ion sources, and a copper ion complexing agent as copper ion sources, glyoxylic acid as a copper ion reducing agent, and a pH conditioner, the present invention. The method is characterized by precipitating and removing sulfuric and oxalic ions in said electroless copper plating solution and keeping an optimum concentration of at least one of sulfuric and oxalic ions in said electroless copper plating solution during plating.